QUALCOMM

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6 June 2013

Ms. Susanna Kooistra
3GPP MCC
ETSI
650, route des Lucioles
06921 Sophia-Antipolis Cedex
France

Subject: Nomination of candidate for the 3GPP TSG RAN WG4 Vice-Chairman

Dear Ms. Kooistra:

QUALCOMM is pleased to nominate Dr. Tingfang Ji for the position of vice-chair of 3GPP TSG-RAN WG4.

Tingfang Ji works for QUALCOMM Technologies, Inc. and represents QUALCOMM Incorporated, an ATIS member, in 3GPP.

A brief curriculum vitae of Tingfang Ji is attached.

Best Regards,

Edward G. Tiedemann Jr.

Edward G. Tiedemann, Jr.
Senior Vice-President, Engineering
QUALCOMM Technologies, Inc.

Tingfang Ji

Tingfang Ji received his B.S. degree in electronic engineering from Tsinghua University, Beijing in 1995 and his Ph.D degree in electrical engineering from the University of Michigan, Ann Arbor in 2001.

From 2001 to 2003 he was a member of the technical staff at Bell Laboratory Advanced Technology department, where he conducted research on 3G cellular networks and Ultra Wide Band. Since 2003, he has been with the Qualcomm Research, where he is currently a principal engineer and manager. From 2003 to 2008, he was one of the key technical contributors to the development of various wideband OFDMA technologies. Since mid-2008, he has been attending 3GPP standards in RAN1/4 and has made significant technical contributions towards the development of LTE and LTE-Advanced. At the same time, he also led a team conducting the system design of a live LTE-Advanced macro/pico/femto eICIC network in a San Diego test bed.

In August 2011 Tingfang was elected as the Vice Chairman of RAN4. He has since chaired half of the RAN4 sessions (RRM/demod) in each meeting. His technical guidance and supervision has led to the successful development of Rel-10/11 baseband requirements specifications.